



# 100% Material Declaration Data Sheet PQ100

PK164 (v1.3.1) October 19, 2006

Material Declaration Data Sheet

**Average Weight: 1.6 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.03472</b>	<b>2.17%</b>
	Silicon	7440-21-3	100.00		0.03472	
<b>Die Attach Material</b>					<b>0.00544</b>	<b>0.34%</b>
	Silver	7440-22-4	78.00		0.0042432	
	Epoxy (EP)	Trade Secret	22.00		0.0011968	
<b>Mold Compound</b>					<b>1.24624</b>	<b>77.89%</b>
	Epoxy Resin (EP)	Trade Secret	9.00		0.1121616	
	Phenolic Resin	Trade Secret	7.00		0.0872368	
	Carbon Black	1333-86-4	0.50		0.0062312	
	SiO2 Filler	60676-86-0	82.50		1.028148	
	Bismuth	7440-69-9	Max 1.00		0.0124624	
<b>Leadframe</b>					<b>0.2856</b>	<b>17.85%</b>
	Copper	7440-50-8	98.85		0.2823156	
	Chromium	7440-47-3	0.30		0.0008568	
	Tin	7440-31-5	0.25		0.000714	
	Zinc	7440-66-6	0.60		0.0017136	
<b>Leadframe Plating</b>					<b>0.0024</b>	<b>0.15%</b>
	Silver	7440-22-4	100.00		0.0024	
<b>Bond Wire</b>					<b>0.00368</b>	<b>0.23%</b>
	Gold	7440-57-5	100.00		0.00368	
<b>Ext. Plating</b>					<b>0.02192</b>	<b>1.37 %</b>
	Tin	7440-31-5	85.00		0.018632	
	Lead	7439-92-1	15.00		0.003288	

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1

## Revision History

The following table shows the revision history for this document.

<b>Date</b>	<b>Revision</b>	<b>Revision</b>
3/23/06	1.0	Initial release.
6/05/06	1.1	100% Material Declaration.
8/16/06	1.2	Corrected all component weights.
9/29/06	1.3	Updated component descriptions.
10/19/06	1.3.1	Editorial change; corrected typo in Substance Description.